



1. Introduction

Even though triacs have been available since the 1960s and are regarded as a mature technology, they remain an extremely popular power control device for AC mains applications because of their low cost and the simplicity of their control circuits. There was even an upsurge in their use from the 1990s due partly to the increased use of domestic appliances with electronic controls. Common examples of these appliances include air and water heaters, vacuum cleaners, refrigerators, washing machines, dishwashers, coffee machines, air conditioning units and most small kitchen appliances.

Despite its maturity, triac technology has not "stood still" since the invention of the first triacs. Triacs have evolved to meet the changing demands of applications. One such important change is the gate sensitivity specification, I_{GT} . Early triac trigger circuits were built using discrete components that could supply substantial currents of 100mA peak or more. These are still relevant today for discrete phase control circuits which use a diac to deliver healthy, well-defined trigger pulses. However, for two main reasons, Integrated Circuit control has become increasingly popular and this required more sensitive gates driven by smaller gate currents.

Firstly, Electro Magnetic Compatibility regulations limit the harmonic currents that can be drawn from the mains and also limit the amount of Radio Frequency Interference that can be generated by appliances. This requires the use of a dedicated zero crossing triac power control IC or, more likely nowadays, a microcontroller with suitable programming to achieve the required functions. One example is where a high harmonic and RFI-generating phase control circuit is replaced by an electrically "quieter" alternative that is suitable for variable power control of higher power or resistive loads. An example of this is a Binary Rate Modulation power controller in which varying full and half mains cycles are conducted symmetrically to ensure very low harmonic currents and zero DC component in the current waveform.

Secondly, more intelligent appliance controls have become common place, such as remote control, soft start, variable timing, automatic power ramp-up & ramp-down and intelligent power control. These would be very complicated, expensive or even impossible to implement using discrete components. Integrated Circuits (microcontrollers) must be used, but they possess a limited drive current capability of 10 or 20mA max. Furthermore, since the IC's supply is sometimes derived from the mains via a basic resistive/capacitive dropper and half-wave rectifier, current availability is limited and the average current demand from the IC's power supply must be minimised. This imposes a limit on the current amplitude and duration available for triggering the triac.

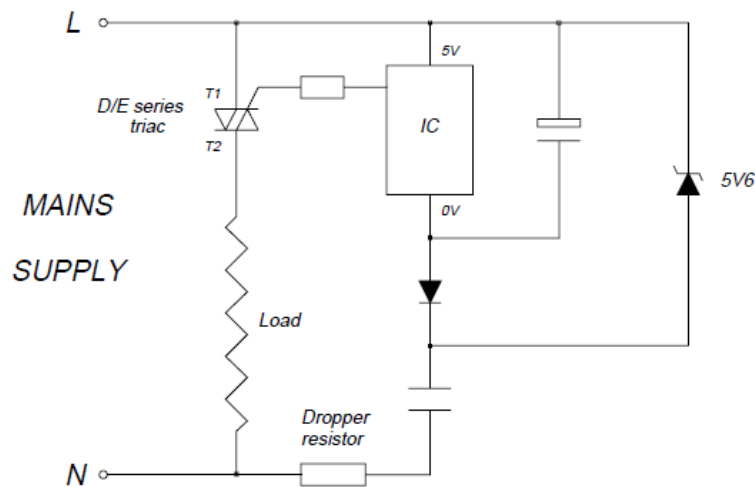


Fig. 1 A typical IC / Triac circuit arrangement

Fig. 1 shows a simple *low-cost* IC-triac arrangement. The 5.6V Zener diode combined with the forward voltage drop of the rectifier diode produce an IC supply close to 5V. The advantages of connecting the Zener as shown instead of directly across the IC are that full wave current is drawn from the mains supply (no DC component), and the forward conduction of the Zener means that the diode never has to support full mains voltage. A cheap, low voltage diode can therefore be used. Attention must be paid, however, to the additional power dissipation in the resistor due to the forward Zener current.

These IC-triac power control applications could not be implemented without sensitive gate triacs. WeEn logic level D series and sensitive gate E series triacs are designed to meet fully the requirements in this established market. For a full selection guide of available types, see Tables 1 and 2 on pages 8, 9 and 10.

2. Gate trigger current, I_{GT}

WeEn's D and E series of the older designed four-quadrant (4Q) triacs are specified to trigger in all four triggering quadrants. 4Q triacs have the unavoidable limitation of being less sensitive and more difficult to trigger in the 4th (T₂-, G+) quadrant. (For example, for the D series, max I_{GT} in quadrant 1, 2, 3 and 4 is 5, 5, 5 and 10mA, and for the E series it is 10, 10, 10 and 25mA). In the 4th quadrant, the ability of triacs to support a high rate of rise of load current (di_T/dt) after turn-on is also limited as di_T/dt can be 10A/ μ s compared with 50A/ μ s or higher in the other three quadrants.

For these two reasons, operation in the 4th quadrant is not recommended and is best avoided. Consequently, WeEn developed a range of three quadrant (3Q) triacs specified to trigger in only 3 quadrants with a specification for $di_T/dt = 100A/\mu$ s in all three quadrants. These are the 3Q Hi-Com triac series with vastly superior immunity to commutation failure / loss of control compared to the more traditional 4Q alternatives. Three-quadrant triacs are the automatic first choice for any application. (For triggering quadrant diagram refer to the Appendix on page 11)

Since the control IC operates on a single rail supply (usually +5V), its outputs are unipolar and therefore can be referenced to the mains circuit in order to source current (positive gate drive) or to

sink current (negative gate drive). Since 4th quadrant triggering should be avoided, the optimum performance will be obtained with negative gate current - i.e. operation in the 2nd (T2+, G-) and 3rd (T2-, G-) triggering quadrants (see Fig. 1).

A triac's I_{GT} increases at lower temperatures and the gate drive circuit must supply enough gate current for the lowest expected operating temperature to guarantee triggering. Fig. 2 shows an example of normalised I_{GT} versus T_j for the 4Q BT136 series D and Fig. 3 for the 3Q BTA310-600D.

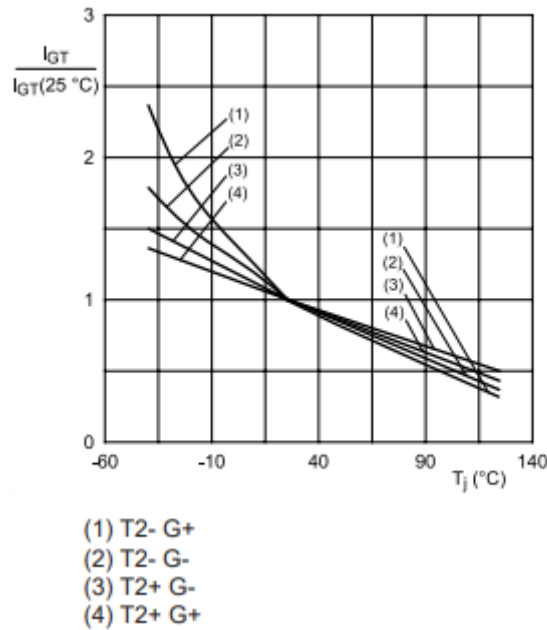


Fig. 2 BT136 series D normalised I_{GT} versus T_j

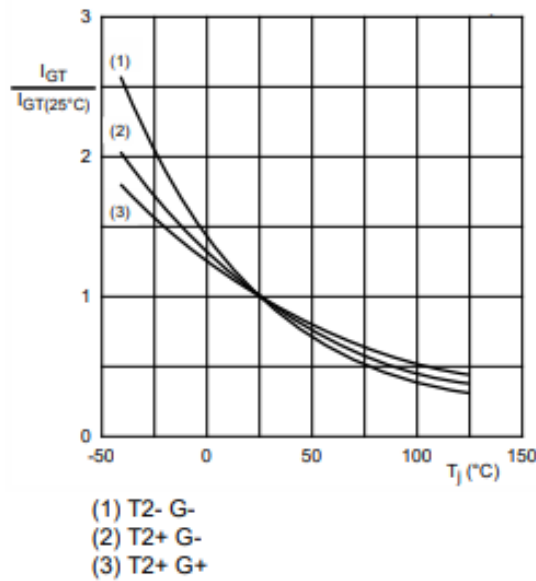


Fig. 3 BTA310 series D normalised I_{GT} versus T_j

3. Latching current, I_L

If the triac is triggered by a gate current at the beginning of a mains half-cycle, the load current will build up gradually from zero. The gate current must not be removed before the triac is latched ON otherwise it will return to the blocking state. Latching occurs when the load current reaches I_L . The gate pulse must therefore be present until the load current has reached I_L .

Just as for I_{GT} , the holding current, I_L also increases at lower temperature. The gate pulse duration must be specified at the lowest expected operating temperature for guaranteed triggering. Fig. 4 shows an example of normalised I_L versus T_j for the 4Q BT136 series D and Fig. 5 for the 3Q BTA310 series D.

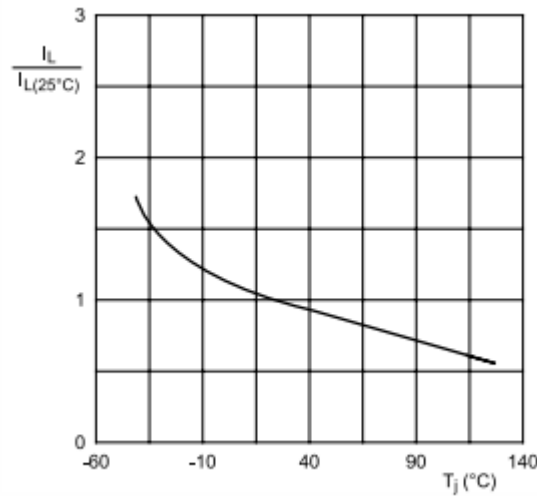


Fig. 4 BT136 series D normalised I_L versus T_j

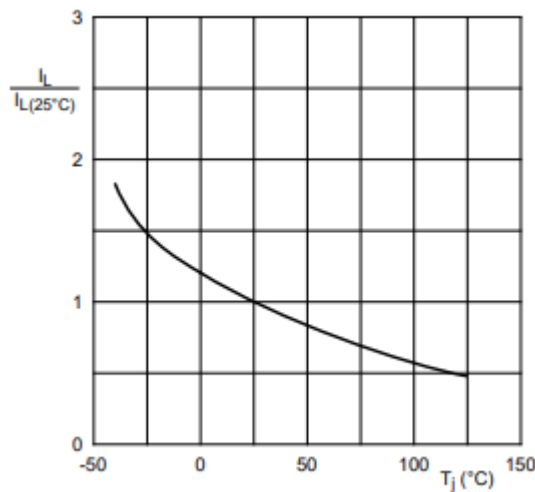


Fig. 5 BTA310 series D normalised I_L versus T_j

How quickly the load current reaches the triac's latching current, I_L will depend on the peak load current and mains frequency. Taken to the extreme case, if the load current is so low that its peak value is equivalent to I_L , it will take one quarter cycle, or 5ms for 50Hz mains, before the triac is latched and the gate pulse can cease.

It is also important to be aware that higher current triacs have a higher latching current, I_L . This could increase switching problems or even lead to the triac never latching ON if the load current is lower than the triac's I_L . So, apart from the higher component cost, it would not be advisable to use a triac whose current rating is very much higher than the load current when a lower current type is available. Tables 1 and 2 on pages 8, 9 and 10, illustrate how I_L varies with the triggering quadrant and triac current rating.

4. Calculating the minimum average triac current

Because the current demand must be minimised in many IC applications, it is necessary to calculate the gate pulse duration to be just long enough to guarantee triac triggering while avoiding unnecessary burden on the IC's power supply. The time to reach I_L , hence the gate pulse duration, can be calculated using the equation:

$$I_L = I_{pk} \times \sin(2\pi ft)$$

Transposing gives:

$$t = 1/(2\pi f) \times \sin^{-1}(I_L/I_{pk})$$

The average gate current supplied by the IC is calculated by multiplying its peak gate current with t/T .

Hence:

$$I_{G(av)} = I_{G(pk)} \times t/T$$

I_L = triac latching current at the lowest expected operating-temperature

I_{pk} = peak load current

t = gate pulse duration

T = gate pulse cycle time.

Note:- Since triac latching current is higher in the 2nd and 4th quadrants, and normal operation for IC triggering is in the 2nd and 3rd quadrants, the gate current calculations must always be based on *the worst-case quadrant 2, I_L condition*.

If the load current is very low and the necessary gate pulse duration imposes too great a burden on the IC's power supply, triggering could be delayed for a few degrees to allow the supply voltage to build up a little. The time to reach I_L will then be shortened by the delay time (true for resistive loads). Now that switching occurs further from the zero crossing, there will be a slightly increased risk of RFI generation, even if the load current is very low as in this case. RFI measurements will show if filtering is necessary to meet the relevant EMC regulations.

5. Holding current, I_H

As the load current reduces towards the end of a mains half cycle, a current, I_H , will be reached when the triac is no longer latched. It will cease to conduct in the absence of a gate current. I_H also increases with reducing temperature. Fig. 6 shows an example of normalised I_H versus T_j for the 4Q BT136 series D and Fig. 7 for the 3Q BTA310 series D.

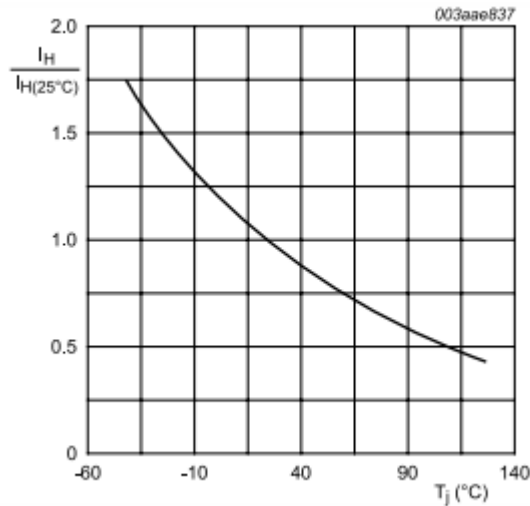


Fig. 6 BT136 series D normalised I_H versus T_j

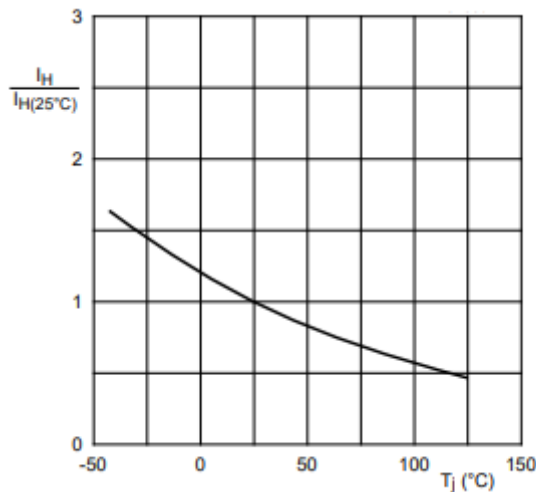
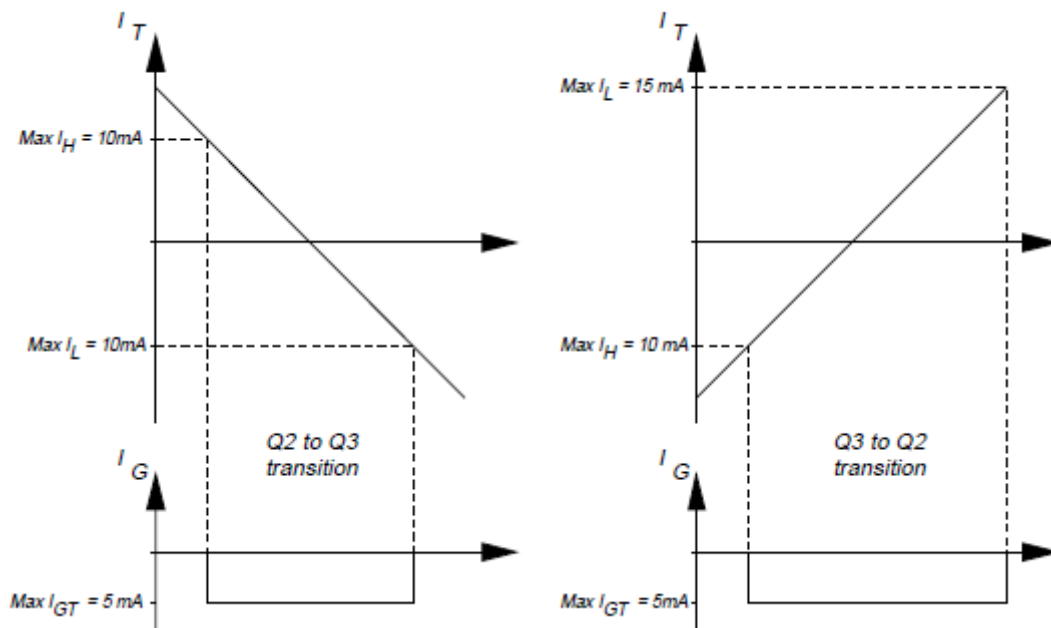


Fig. 7 BTA310 series D normalised I_H versus T_j

In some IC applications where the triac is used as a power switch, for example a precision electronic thermostat for a refrigerator compressor, continuous conduction must be maintained through the current zero crossing. (This is essential to prevent glitches and RFI generation). Continuous conduction is achieved by monitoring the load current and applying a gate pulse before the triac's I_H is reached and maintaining the pulse until the current has passed through zero and risen to the triac's I_L in the alternate quadrant. This condition must be met at the lowest expected operating temperature for continuous glitch-free conduction under worst-case conditions.

The holding current, I_H increases for the larger E series triacs whereas the most sensitive D series triacs are designed to maintain a consistent, low I_H of 10mA @ 25°C even for the higher current rating.

Fig. 8 illustrates triac load current zero-crossing and the minimum gate pulse required for continuous conduction through the max I_H and I_L points. The diagram illustrates how I_H remains constant in different quadrants. The point made earlier about how I_L varies in different quadrants is illustrated by the higher I_L in the 2nd quadrant (T2+, G-). Note that the I_G duration must meet this worst-case condition.



Logic level selection guide (at June 2020)

Table 1. 3Q Logic level and sensitive gate triacs

Triac Type Number	Gate Sensitivity	$I_{T(RMS)}$ (A)	V_{DRM} (V)	$I_{GT(max)}$ (mA)	$I_{L(max)}$ (mA)	$I_{H(max)}$ (mA)	Package
BTA2008W	D	0.8	600D & 800D	5	20	10	SOT223
BTA2008	D/E	0.8	600D/E & 800D	5/10	12/20	12	TO92
BTA2008	D	0.8	1000D	5	20	10	TO92
BTA201	E	1	600E & 800E	10	20	12	TO92
BTA201W	E	1	600E & 800E	10	12	12	SOT223
BTA202X	D/E	2	600D/E & 800D/E	5/10	5/20	10/12	TO220F
BTA204	D/E	4	600D/E & 800E	5/10	9/18	6/12	TO220AB
BTA204S	D/E	4	600D/E & 800E	5/10	9/18	6/12	DPAK
BTA204W	D/E	4	600D/E & 800E	5/10	9/18	6/12	SOT223
BTA204X	D/E	4	600D/E & 800E	5/10	9/18	6/12	TO220F
BTA206	E	6	800E	10	30	15	TO220AB
BTA206X	E	6	800E	10	30	15	TO220F
BTA208	D/E	8	600D/E & 800E	5/10	25/18	15/12	TO220AB
BTA208S	D/E	8	600D/E & 800E	5/10	25/30	15/25	DPAK
BTA208X	D/E	8	600D/E & 800E	5/10	9/18	6/12	TO220F
BTA310	D/E	10	600D/E & 800D/E	5/10	15/30	10/15	TO220AB
BTA310X	D/E	10	600D/E & 800D/E	5/10	15/30	10/15	TO220F
BTA410	E	10	600E & 800E	10	30	15	TO220AB
BTA410X	E	10	600E & 800E	10	30	15	TO220F
BTA410Y	E	10	600E & 800E	10	30	15	IITO220
BTA312	D/E	12	600D/E & 800E	5/10	15/30	10/15	TO220AB
BTA312X	D/E	12	600D/E & 800E	5/10	15/30	10/15	TO220F
BTA312B	D/E	12	600D/E & 800E	5/10	15/30	10/15	D ² PAK
BTA412Y	E	12	600E & 800E	10	35	10	IITO220
BTA316	D/E	16	600D/E & 800E	5/10	30/30	15/15	TO220AB
BTA316X	E	16	600E & 800E	10	30	25	TO220F
BTA316B	E	16	600E & 800E	10	30	15	D ² PAK

Fig. 8 Example of relationship between I_L , I_H and I_{GT} (for BT136 series D at 25°C)

Table 2. 4Q Logic level and sensitive gate triacs

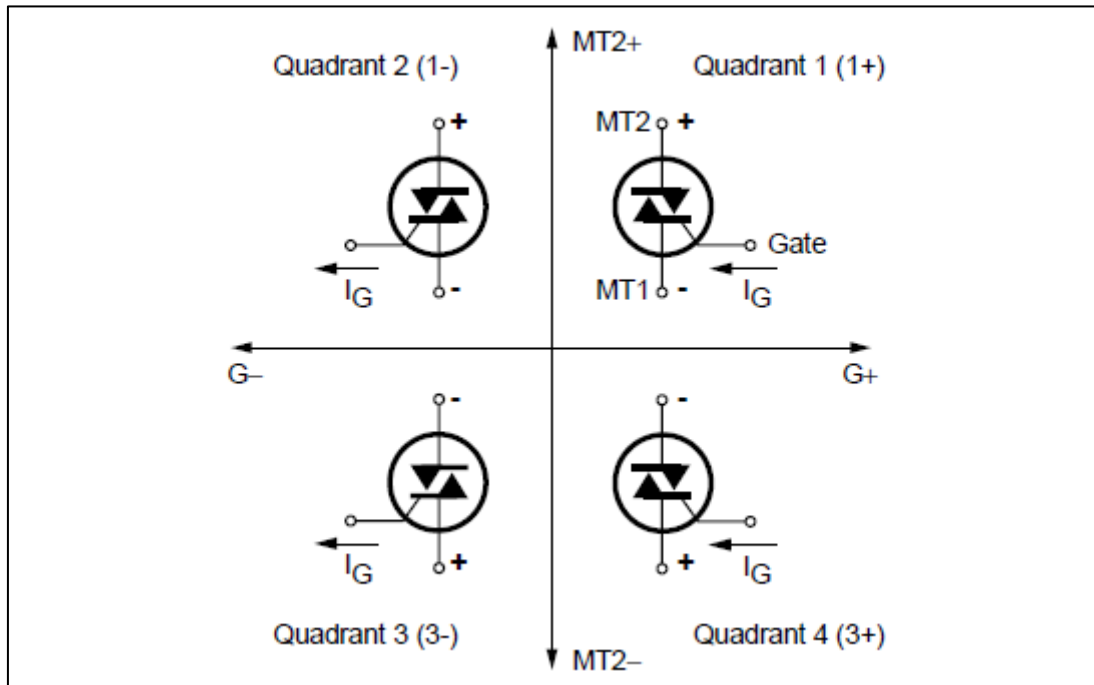
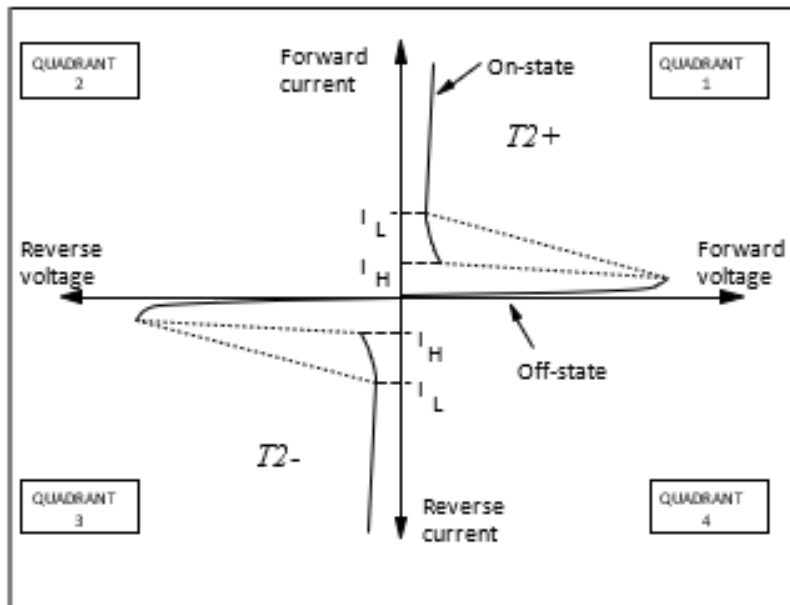
Triac Type Number	Gate Sensitivity	$I_{T(RMS)}$ (A)	V_{DRM} (V)	$I_{GT(max)}$ (mA)	$I_{L(max)}$ (mA)	$I_{H(max)}$ (mA)	Package
MAC97A6	very sensitive	0.6	400	5,5,5,7	10	10	TO92
MAC97A8	very sensitive	0.8	600	5,5,5,7	10	10	TO92
BT131W	very sensitive	1	600	3,3,3,7	8	5	SOT223
BT131	very sensitive	1	600 & 800	3,3,3,7	8	5	TO92
BTA131	D/E	1	600D/E & 800D/E	5,5,5,7/10	20/25	10/10	TO92
Z0103MA	very sensitive	1	600	3,3,3,5	15	7	TO92
Z0103NA	very sensitive	1	800	3,3,3,5	15	7	TO92
Z0103MN	very sensitive	1	600	3,3,3,5	15	7	SOT223
Z0103NN	very sensitive	1	800	3,3,3,5	15	7	SOT223
Z0107MA	very sensitive	1	600	5,5,5,7	20	10	TO92
Z0107NA	very sensitive	1	800	5,5,5,7	20	10	TO92
Z0107MN	very sensitive	1	600	5,5,5,7	20	10	SOT223
Z0107NN	very sensitive	1	800	5,5,5,7	20	20	SOT223
Z0109MA	sensitive	1	600	10	25	10	TO92
Z0109NN	sensitive	1	800	10	25	20	TO92
Z0109MN	sensitive	1	600	10	25	10	SOT223
Z0109NN	sensitive	1	800	10	25	10	SOT223
Z0103MA0	sensitive	1	600	3,3,3,5	20	7	TO92
Z0103NA0	sensitive	1	800	3,3,3,5	20	7	TO92
Z0103MN0	sensitive	1	600	3,3,3,5	20	7	SOT223
Z0103NN0	sensitive	1	800	3,3,3,5	20	7	SOT223
Z0107MA0	sensitive	1	600	5,5,5,7	25	10	TO92
Z0107NA0	sensitive	1	800	5,5,5,7	25	10	TO92
Z0107MN0	sensitive	1	600	5,5,5,7	25	10	SOT223
Z0107NN0	sensitive	1	800	5,5,5,7	25	10	SOT223
Z0109MA0	sensitive	1	600	10	30	10	TO92
Z0109NA0	sensitive	1	800	10	30	10	TO92
Z0109MN0	sensitive	1	600	10	30	10	SOT223
Z0109NN0	sensitive	1	800	10	30	10	SOT223
BT132	D	1	600	5,5,5,10	15	10	TO92
BT134W	D	1	600D	5,5,5,10	15	10	SOT223
BT134W	E	1	600E & 800E	10,10,10,25	20	15	SOT223
BT134	D	4	600D	5,5,5,10	15	10	SOT82
BT134	E	4	600E & 800E	10,10,10,25	20	15	SOT82
BT136	D	4	600D	5,5,5,10	15	10	TO220AB
BT136X	D	4	600D	5,5,5,10	15	10	TO220F
BT136S	D	4	600D	5,5,5,10	15	10	DPAK
BT136	E	4	600E & 800E	10,10,10,25	20	15	TO220AB
BT136X	E	4	600E & 800E	10,10,10,25	20	15	TO220F
BT136S	E	4	600E & 800E	10,10,10,25	20	15	DPAK
BT136B	E	4	600E & 800E	10,10,10,25	20	15	D ² PAK

**Table 2. 4Q Logic level and sensitive gate triacs
(continued)**

Triac Type Number	Gate Sensitivity	$I_{T(RMS)}$ (A)	V_{DRM} (V)	$I_{GT(max)}$ (mA)	$I_{L(max)}$ (mA)	$I_{H(max)}$ (mA)	Package
BT234	D	4	600D & 800D	5,5,5,10	15	6	TO220AB
BT234	E	4	600E & 800E	10,10,10,25	25	15	TO220AB
BT234X	D	4	600D & 800D	5,5,5,10	15	6	TO220F
BT234X	E	4	600E & 800E	10,10,10,25	25	15	TO220F
BT137	D	8	600D	5,5,5,10	20	10	TO220AB
BT137	E	8	600E & 800E	10,10,10,25	35	20	TO220AB
BT137X	D	8	600D	5,5,5,10	20	10	TO220F
BT137X	E	8	600E & 800E	10,10,10,25	35	20	TO220F
BT137S	D	8	600D	5,5,5,10	20	10	DPAK
BT137S	E	8	600E & 800E	10,10,10,25	35	20	DPAK
BT137B	E	8	600E	10,10,10,25	35	20	D ² PAK
BT138	D	12	600D	5,5,5,10	20	10	TO220AB
BT138	E	12	600E & 800E	10,10,10,25	40	30	TO220AB
BT138X	D	12	600D	5,5,5,10	20	10	TO220F
BT138X	E	12	600E & 800E	10,10,10,25	40	30	TO220F
BT138B	E	12	600E & 800E	10,10,10,25	40	30	D ² PAK
BT138Y	E	12	600E & 800E	10,10,10,25	40	30	IITO220AB
BT139	E	16	600E & 800E	10,10,10,25	40	45	TO220AB
BT139X	E	16	600E	10,10,10,25	40	45	TO220F
BT139B	E	16	600E & 800E	10,10,10,25	40	45	D ² PAK

7. Appendix

1. Triac V/I characteristics and triggering quadrants



2. WeEn Semiconductors Product Selection Guide:-

<http://www.ween-semi.com/sites/default/files/inline-files/WeEn20190626.pdf>

Revision history

Rev	Date	Description
v.01	20200701	New Application Note
v.02	20200716	Addition to 1 st paragraph on page 7

Contact information

For more information and sales office addresses please visit: <http://www.ween-semi.com>

Legal information

Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors takes no responsibility for the content in this document if provided by an information source outside of WeEn Semiconductors.

In no event shall WeEn Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages

are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, WeEn Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of WeEn Semiconductors.

Right to make changes — WeEn Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — WeEn Semiconductors products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an WeEn Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. WeEn Semiconductors and its suppliers accept no liability for inclusion and/or use of WeEn Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. WeEn Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using WeEn Semiconductors products, and WeEn Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the WeEn Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third-party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

WeEn Semiconductors does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third-party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using WeEn Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third-party customer(s). WeEn does not accept any liability in this respect.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Evaluation products — This product is provided on an "as is" and "with all faults" basis for evaluation purposes only. WeEn Semiconductors, its affiliates and their suppliers expressly disclaim all warranties, whether express, implied or statutory, including but not limited to the implied warranties of non-infringement, merchantability and fitness for a particular purpose. The entire risk as to the quality, or arising out of the use or performance, of this product remains with customer.

In no event shall WeEn Semiconductors, its affiliates or their suppliers be liable to customer for any special, indirect, consequential, punitive or incidental damages (including without limitation damages for loss of business, business interruption, loss of use, loss of data or information, and the like) arising out of the use of or inability to use the product, whether or not based on tort (including negligence), strict liability, breach of contract, breach of warranty or any other theory, even if advised of the possibility of such damages.

Notwithstanding any damages that customer might incur for any reason whatsoever (including without limitation, all damages referenced above and all direct or general damages), the entire liability of WeEn Semiconductors, its affiliates and their suppliers and customer's exclusive remedy for all of the foregoing shall be limited to actual damages incurred by customer based on reasonable reliance up to the greater of the amount actually paid by customer for the product or five dollars (US\$5.00). The foregoing limitations, exclusions and disclaimers shall apply to the maximum extent permitted by applicable law, even if any remedy fails of its essential purpose.

Translations — A non-English (translated) version of a document is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

Contents

1.	Introduction	1
2.	Gate trigger current, I_{GT}	2
3.	Latching current, I_L	4
4.	Calculating the minimum average triac current	5
5.	Holding current, I_H	6
6.	Logic level selection guide (at June 2020)	8
7.	Appendix	11
	1. Triac V/I characteristics & triggering quadrants	11
	2. WeEn Semiconductors Product Selection Guide (hyperlink)	11
	Revision history and contact information	13
	Legal information	13
	Definitions	13
	Disclaimers	13
	Trademarks	13
	Contents	14

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section "Legal information".

© WeEn 2020.

All rights reserved

For more information, please visit: <http://www.ween-semi.com>

Date of release: 16 July 2020

Document identifier: WAN011